



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	IPBE65R099CFD7A	<b>Issued</b>	24. February 2022
<b>MA#</b>	MA005708736		
<b>Package</b>	PG-TO263-7-11	<b>Weight*</b>	1557.75 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	8.278	0.53	0.53	5314	5314
leadframe	inorganic material	phosphorus	7723-14-0	0.257	0.02		165	
	non noble metal	iron	7439-89-6	0.856	0.05		549	
	non noble metal	copper	7440-50-8	854.720	54.89	54.96	548690	549404
wire	non noble metal	aluminium	7429-90-5	3.720	0.24	0.24	2388	2388
encapsulation	inorganic material	zinc oxide	1314-13-2	5.675	0.36		3643	
	miscellaneous	miscellaneous	-	22.700	1.46		14572	
	plastics	epoxy resin	-	85.124	5.46		54645	
	inorganic material	silicon dioxide	60676-86-0	453.992	29.14	36.42	291442	364302
lead finish	non noble metal	tin	7440-31-5	9.890	0.63	0.63	6349	6349
plating	inorganic material	phosphorus	7723-14-0	0.010			7	
	non noble metal	nickel	7440-02-0	4.272	0.27	0.27	2743	2750
solder	non noble metal	tin	7440-31-5	0.115	0.01		74	
	noble metal	silver	7440-22-4	0.144	0.01		92	
	non noble metal	lead	7439-92-1	5.483	0.35	0.37	3520	3686
heatspreader	inorganic material	phosphorus	7723-14-0	0.031			20	
	non noble metal	iron	7439-89-6	0.103	0.01		66	
	non noble metal	copper	7440-50-8	102.377	6.57	6.58	65721	65807
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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